

S8550

Rev.E Mar.-2016

DATA SHEET

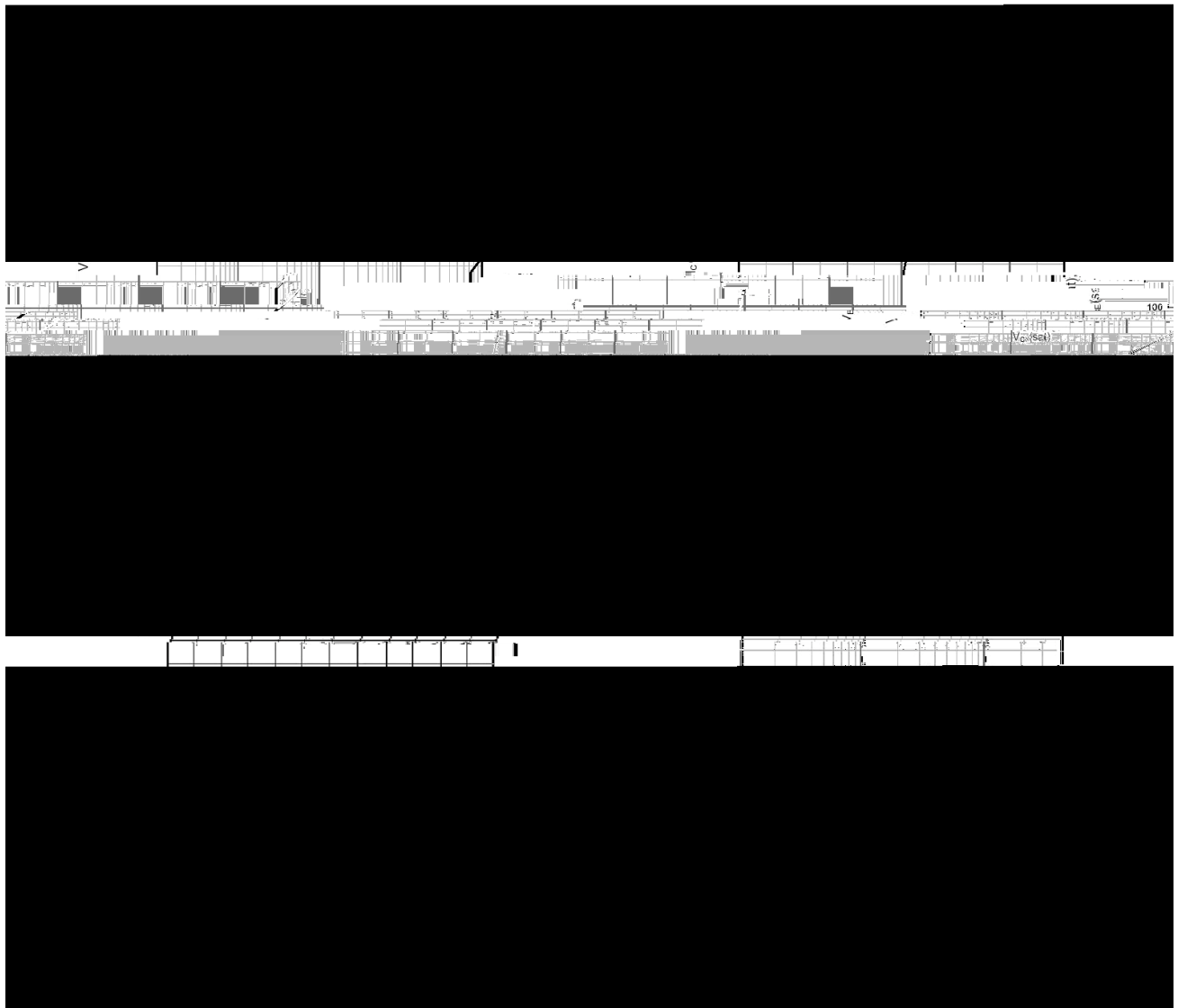
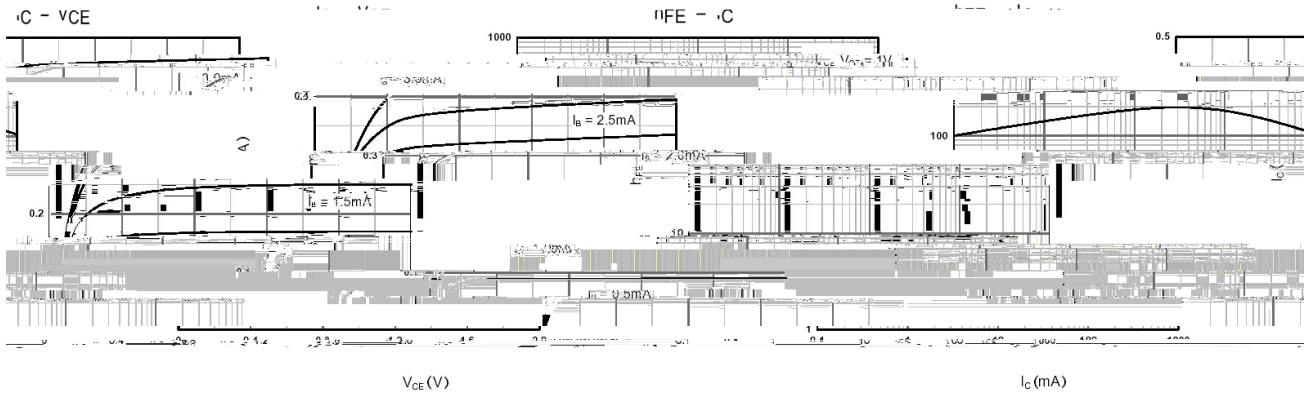
/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-40	V
Collector to Emitter Voltage	V_{CEO}	-25	V
Emitter to Base Voltage	V_{EBO}	-6.0	V
Collector Current - Continuous	I_C	-800	mA
Base Current - Continuous	I_B	-200	mA
Collector Power Dissipation	P_C	625	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C=-0.1mA$ $I_E=0$	-40			V
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C=-2.0mA$ $I_B=0$	-25			V
Emitter to Base Breakdown Voltage	V_{EBO}	$I_E=-0.1mA$ $I_C=0$	-6.0			V
Collector Cut-Off Current	I_{CBO}	$V_{CB}=-35V$ $I_E=0$			-0.1	A
Emitter Cut-Off Current	I_{EBO}	$V_{EB}=-6.0V$ $I_C=0$			-0.1	A
DC Current Gain	$h_{FE(1)}$	$V_{CE}=-1.0V$ $I_C=-100mA$	85		300	
	$h_{FE(2)}$	$V_{CE}=-1.0V$ $I_C=-500mA$	40			
	$h_{FE(3)}$	$V_{CE}=-1.0V$ $I_C=-5.0mA$	45			
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=-500mA$ $I_B=-50mA$		-0.28	-0.6	V
Base to Emitter Saturation Voltage	$V_{BE(sat)}$	$I_C=-500mA$ $I_B=-50mA$		-0.98	-1.2	V
Base to Emitter Voltage	V_{BE}	$V_{CE}=-1.0V$ $I_C=-10mA$		-0.66	-1.0	V
Transition Frequency	f_T	$V_{CE}=-10V$ $I_C=-50mA$	100	200		MHz
Collector Output Capacitance	C_{ob}	$V_{CB}=-10V$ $f=1.0MHz$ $I_E=0$		15		pF

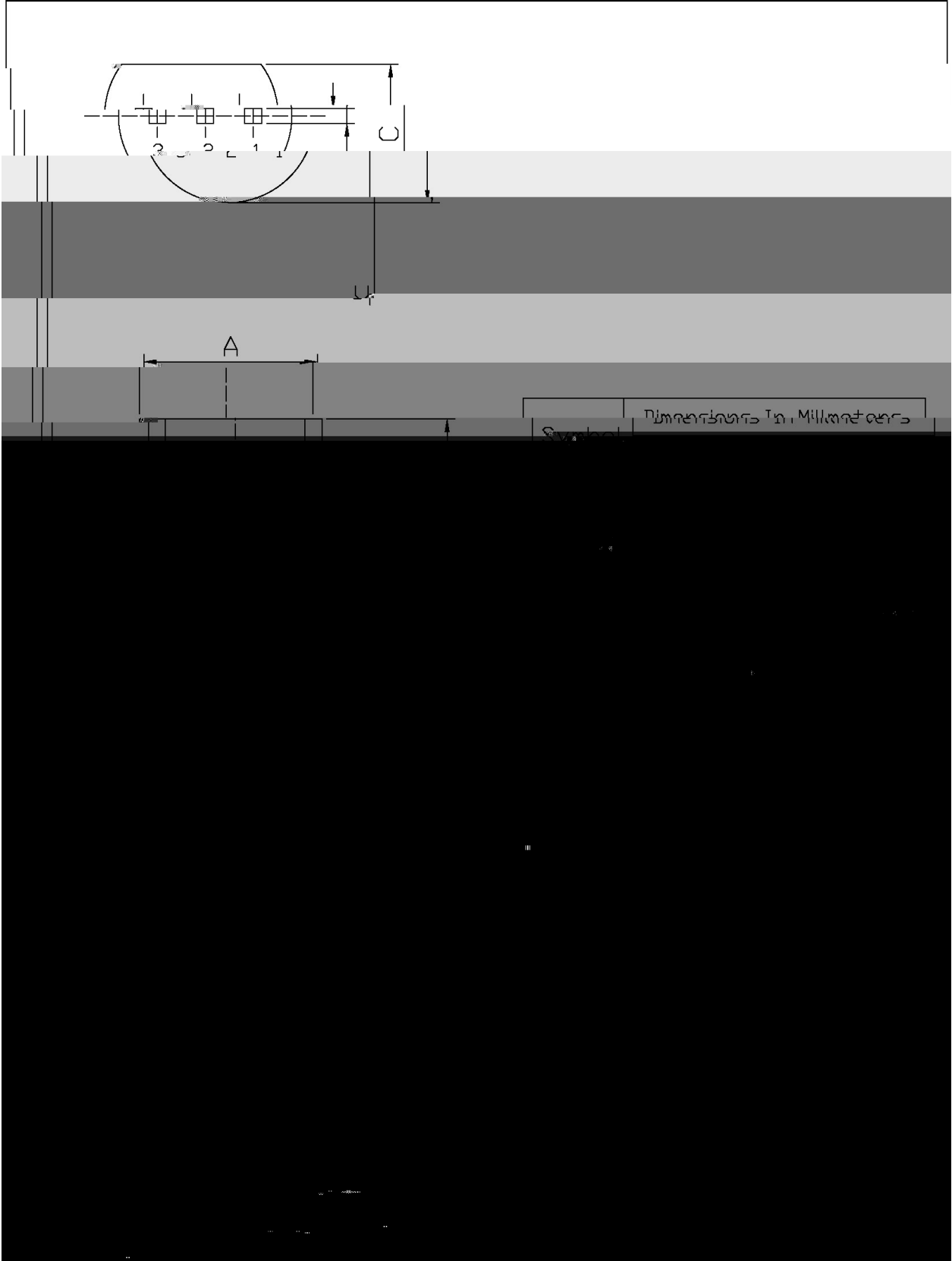
/ Electrical Characteristic Curve



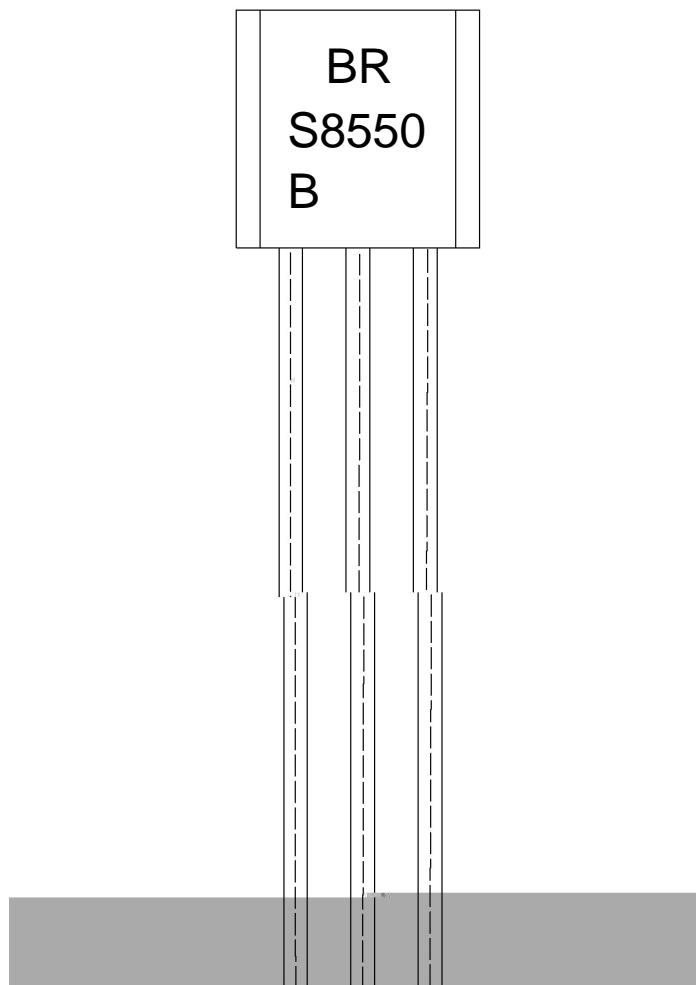
/ Package Dimensions

TO-92

Unit: mm



/ Marking Instructions



BR

S8550

B: h_{FE}

Note:

BR: Company Code.

S8550: Product Type.

B: h_{FE} Classifications Symbol.

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



- | | | | | | | |
|---|-------|-----|-----------|--------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | Note: | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 | | 5±0.5sec; | | 2.Peak Temp.:255±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 /sec. | | 3. Cooling Speed: 2~10 /sec. | |

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. $Tf0.56Db2fTj/TT2$ 1 Tf2 0 TD-0.0005;